

## N-Channel 60 V (D-S) MOSFET



### FEATURES

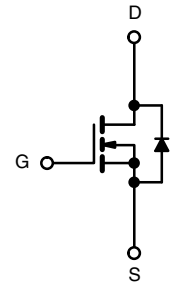
- TrenchFET® power MOSFET
- Maximum 175 °C junction temperature
- Very low  $Q_{gd}$  reduces power loss from passing through  $V_{plateau}$
- 100 %  $R_g$  and UIS tested
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
FREE

### APPLICATIONS

- Power supply  
- Secondary synchronous rectification
- DC/DC converter
- Power tools
- Motor drive switch
- DC/AC inverter
- Battery management
- OR-ing / e-fuse



N-Channel MOSFET

### PRODUCT SUMMARY

$V_{DS}$ (V)	60
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10$ V	0.00175
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 7.5$ V	0.00220
$Q_g$ typ. (nC)	141
$I_D$ (A)	150 <sup>d</sup>
Configuration	Single

### ORDERING INFORMATION

Package	TO-263
Lead (Pb)-free and halogen-free	SUM50010E-GE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	60	V
Gate-source voltage	$V_{GS}$	$\pm 20$	
Continuous drain current ( $T_J = 150$ °C)	$I_D$	$T_C = 25$ °C	150 <sup>d</sup>
		$T_C = 70$ °C	150 <sup>d</sup>
Pulsed drain current ( $t = 100$ $\mu$ s)	$I_{DM}$	500	A
Avalanche current	$I_{AS}$	60	
Single avalanche energy <sup>a</sup>	$E_{AS}$	180	mJ
Maximum power dissipation <sup>a</sup>	$P_D$	$T_C = 25$ °C	375 <sup>b</sup>
		$T_C = 125$ °C	125 <sup>b</sup>
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +175	°C

### THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-ambient (PCB mount) <sup>c</sup>	$R_{thJA}$	40	°C/W
Junction-to-case (drain)	$R_{thJC}$	0.4	

#### Notes

- Duty cycle  $\leq 1$  %
- See SOA curve for voltage derating
- When mounted on 1" square PCB (FR4 material)
- Package limited



SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2	-	4	
Gate-body leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	$\pm 250$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	150	
		$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	5	mA
On-state drain current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 10\text{ V}, V_{GS} = 10\text{ V}$	120	-	-	A
Drain-source on-state resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 30\text{ A}$	-	0.00145	0.00175	$\Omega$
		$V_{GS} = 7.5\text{ V}, I_D = 20\text{ A}$	-	0.00183	0.00220	
Forward transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 30\text{ A}$	-	120	-	S
<b>Dynamic <sup>b</sup></b>						
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 30\text{ V}, f = 1\text{ MHz}$	-	10 895	-	$\mu\text{F}$
Output capacitance	$C_{oss}$		-	2420	-	
Reverse transfer capacitance	$C_{rss}$		-	85	-	
Total gate charge <sup>c</sup>	$Q_g$	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V}, I_D = 20\text{ A}$	-	141	212	nC
Gate-source charge <sup>c</sup>	$Q_{gs}$		-	43.6	-	
Gate-drain charge <sup>c</sup>	$Q_{gd}$		-	19.1	-	
Output charge	$Q_{oss}$	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}$	-	143	215	
Gate resistance	$R_g$	$f = 1\text{ MHz}$	0.24	1.2	2.4	$\Omega$
Turn-on delay time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 3\text{ }\Omega$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	-	28	56	ns
Rise time <sup>c</sup>	$t_r$		-	12	24	
Turn-off delay time <sup>c</sup>	$t_{d(off)}$		-	50	100	
Fall time <sup>c</sup>	$t_f$		-	13	26	
<b>Drain-Source Body Diode Ratings and Characteristics <sup>b</sup> (<math>T_C = 25\text{ }^\circ\text{C}</math>)</b>						
Pulsed current ( $t = 100\text{ }\mu\text{s}$ )	$I_{SM}$		-	-	250	A
Forward voltage <sup>a</sup>	$V_{SD}$	$I_F = 10\text{ A}, V_{GS} = 0\text{ V}$	-	0.8	1.5	V
Reverse recovery time	$t_{rr}$	$I_F = 34\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	-	75	150	ns
Peak reverse recovery charge	$I_{RM(REC)}$		-	2.8	5.6	A
Reverse recovery charge	$Q_{rr}$		-	0.12	0.24	$\mu\text{C}$
Reverse recovery fall time	$t_a$		-	38	-	ns
Reverse recovery rise time	$t_b$		-	37	-	

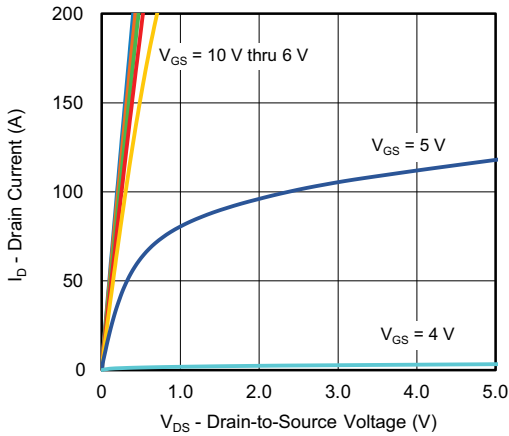
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$   
b. Guaranteed by design, not subject to production testing  
c. Independent of operating temperature

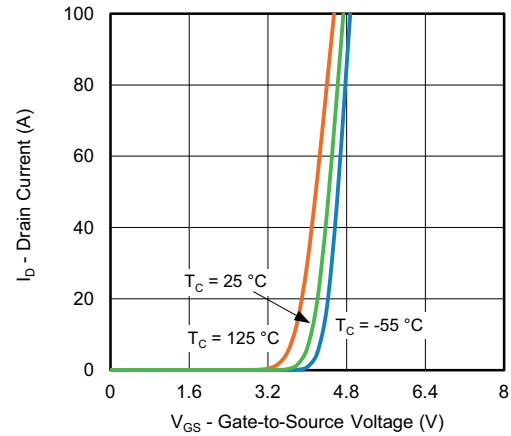
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



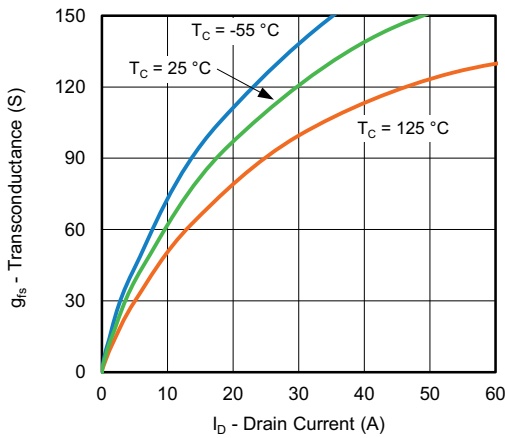
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



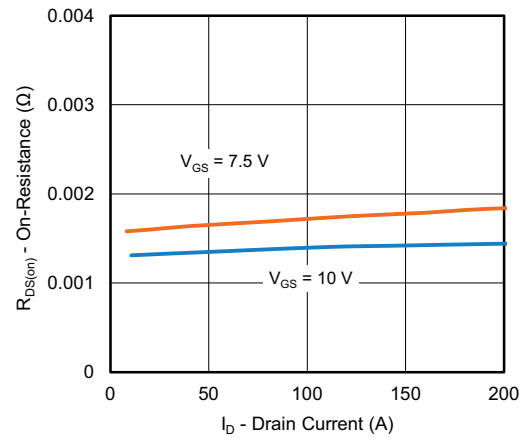
Output Characteristics



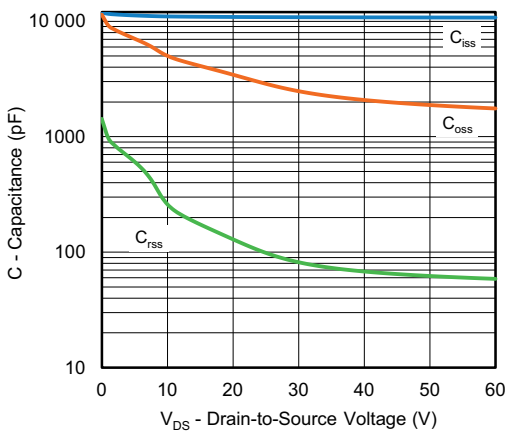
Transfer Characteristics



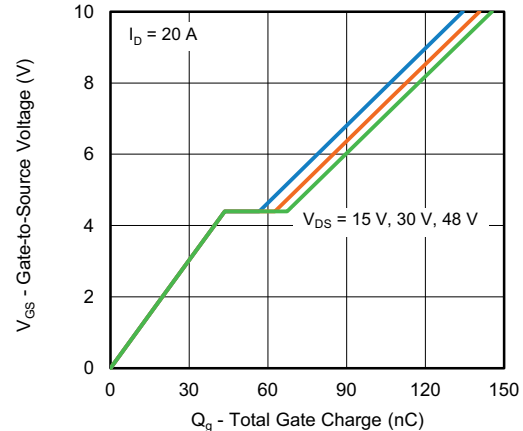
Transconductance



On-Resistance vs. Drain Current



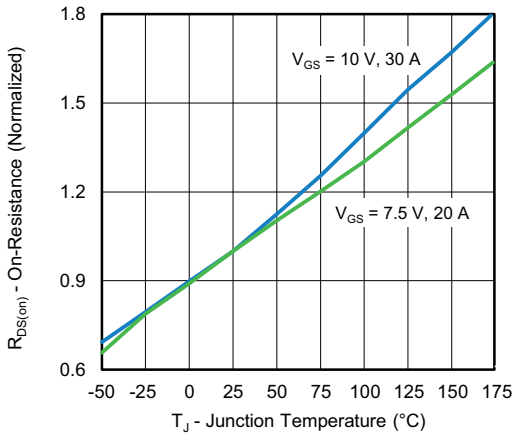
Capacitance



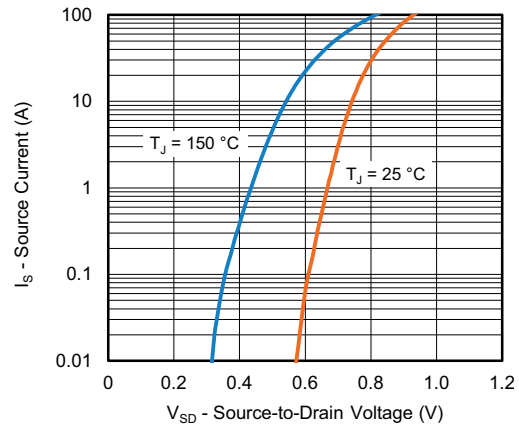
Gate Charge



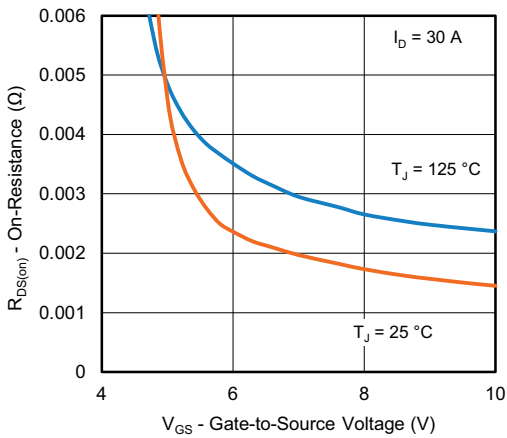
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



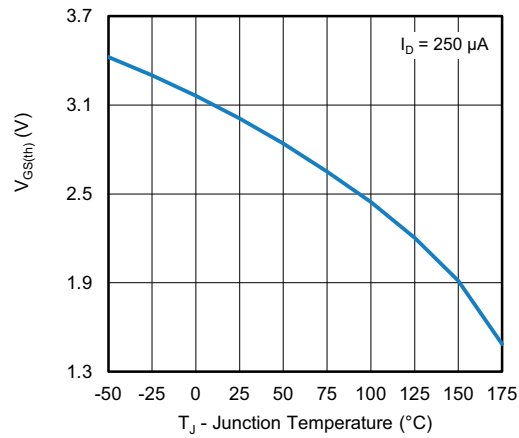
On-Resistance vs. Junction Temperature



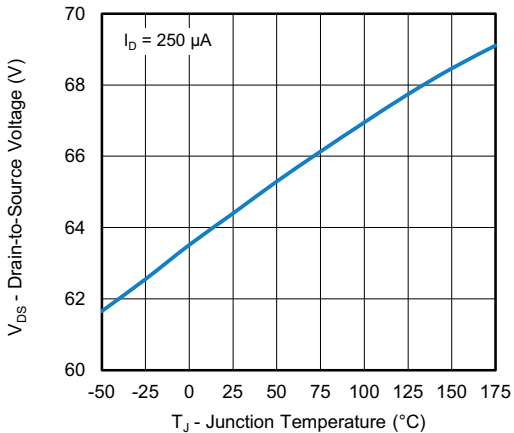
Source Drain Diode Forward Voltage



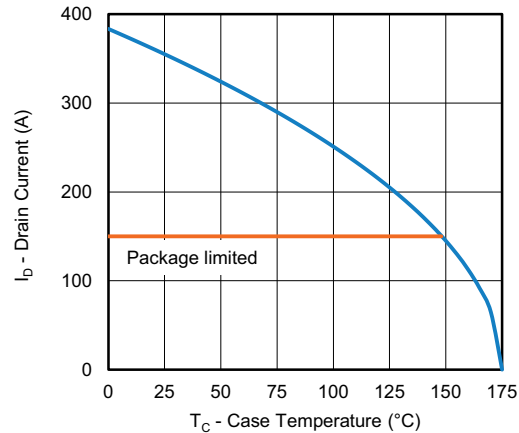
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



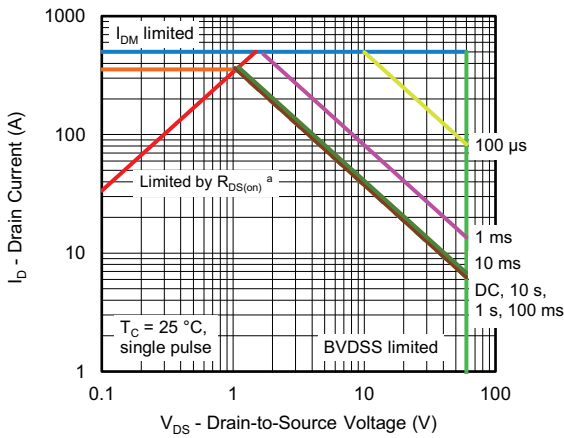
Drain Source Breakdown vs. Junction Temperature



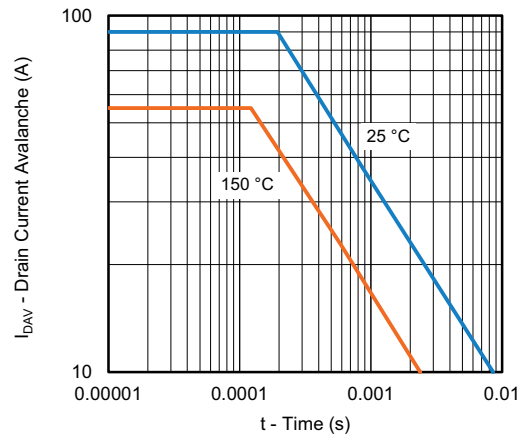
Current De-rating



**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



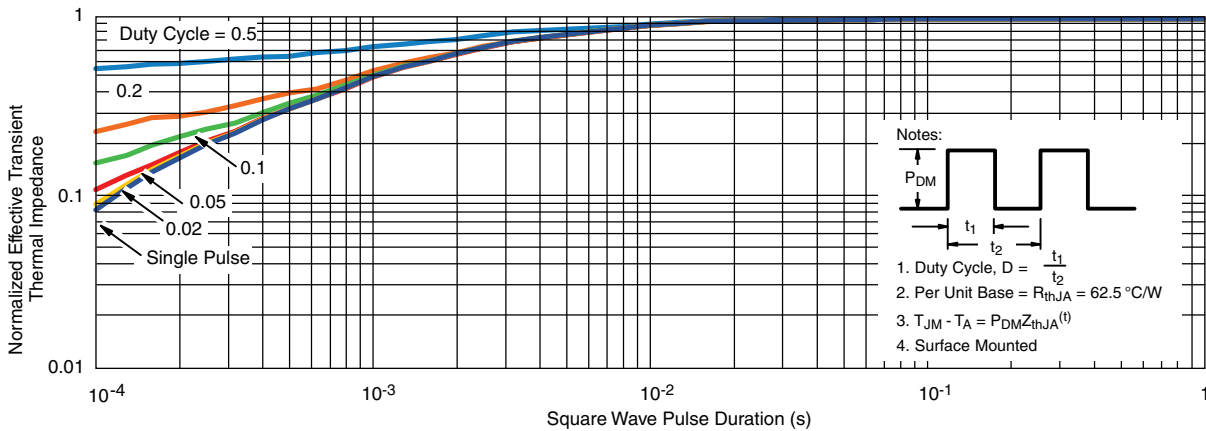
**Safe Operating Area**



**Single Pulse Avalanche Current Capability vs. Time**

**Note**

a.  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



**Normalized Thermal Transient Impedance, Junction-to-Case**

**Note**

- The characteristics shown in the two graphs
    - Normalized Transient Thermal Impedance Junction to Ambient ( $25\text{ }^\circ\text{C}$ )
    - Normalized Transient Thermal Impedance Junction to Case ( $25\text{ }^\circ\text{C}$ )
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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# TO-263 (D<sup>2</sup>PAK): 3-LEAD



DIM.	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	0.160	0.190	4.064	4.826	
b	0.020	0.039	0.508	0.990	
b1	0.020	0.035	0.508	0.889	
b2	0.045	0.055	1.143	1.397	
c*	Thin lead	0.013	0.018	0.330	0.457
	Thick lead	0.023	0.028	0.584	0.711
c1	Thin lead	0.013	0.017	0.330	0.431
	Thick lead	0.023	0.027	0.584	0.685
c2	0.045	0.055	1.143	1.397	
D	0.340	0.380	8.636	9.652	
D1	0.220	0.240	5.588	6.096	
D2	0.038	0.042	0.965	1.067	
D3	0.045	0.055	1.143	1.397	
D4	0.044	0.052	1.118	1.321	
E	0.380	0.410	9.652	10.414	
E1	0.245	-	6.223	-	
E2	0.355	0.375	9.017	9.525	
E3	0.072	0.078	1.829	1.981	
e	0.100 BSC		2.54 BSC		
K	0.045	0.055	1.143	1.397	
L	0.575	0.625	14.605	15.875	
L1	0.090	0.110	2.286	2.794	
L2	0.040	0.055	1.016	1.397	
L3	0.050	0.070	1.270	1.778	
L4	0.010 BSC		0.254 BSC		
M	-	0.002	-	0.050	
ECN: T13-0707-Rev. K, 30-Sep-13					
DWG: 5843					

**Notes**

- Plane B includes maximum features of heat sink tab and plastic.
- No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- Pin-to-pin coplanarity max. 4 mils.
- \*: Thin lead is for SUB, SYB.  
Thick lead is for SUM, SYM, SQM.
- Use inches as the primary measurement.
- This feature is for thick lead.

**RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads  
Dimensions in Inches/(mm)

[Return to Index](#)



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